

Solder Resist

Solder resist (solder mask) is required on both external faces of the printed board, it shall meet the qualification/conformance IPC-SM-840 class H. Coverage, cure and adhesion shall be as defined in paragraphs 3.8.1 to 3.8.3 of IPC-6012, *except* that no encroachment of solder resist is allowed on any surface mount or ball grid lands, **and that ALL pad patterns have solder resist slivers between individual pads. The height of the solder resist should not cause any mounting problems for surface mount components.**

Solder resist data is provided as per IPC-7351 standard, 1:1 with the land size, the manufacturer is to oversize these solder resist openings commensurate with their manufacturing procedures ensuring that *ALL* the above requirements are met, the amount of oversize to take into account the minimum track and gap dimensions as shown on the Printed Boards Master Drawing. Solder resist not related to a component pad is not to be enlarged.